High Voltage Low Power Consumption LDO

MD7601 Series

CMOS Voltage Regulator

1A



MD7601 Series is a high voltage (up to 40V) low power low dropout voltage regulator (LDO) manufactured in CMOS processes. It can deliver up to 1A of current while consuming only 12uA of quiescent current. It consists of a reference voltage generator, an error amplifier, a current foldback circuit, and a phase compensation circuit plus a driver transistor.

■ FEATURES

- Ultra-low Quiescent Current: 12uA
- Maximum Input Voltage: 40V
- Output Voltage Highly Accurate: ±2%
- Maximum Output Current: 1A
- Dropout Voltage: 10mV@Iout=10mA
- \bullet Temperature Stability: ±50ppm/ $^\circ\!\mathrm{C}$
- Protections Circuits: Current Limiter, Foldback, Thermal shutdown
- Output Capacitor: Low ESR Ceramic Capacitor Compatible

APPLICATIONS

Product Selections

- Smart wearer
- Long-life battery-powered devices
- Portable mobile devices, such as mobile phones, cameras, and so on
- Wireless communication equipment

Туре	Output Voltage (note 1*)	Current Limit	Accuracy	Package	MARKING	
				(note 2*)	(note 3*)	
MD7601A30	3.0V	1.8A	±2%	TO-252	₩7601A30	
MD7601A33	3.3V	1.8A	±2%	TO-252	₩7601A33	
MD7601A36	3.6V	1.8A	±2%	TO-252	₩7601A36	
MD7601A40	4.0V	1.8A	±2%	TO-252	₩7601A40	
MD7601A50	5.0V	1.8A	±2%	TO-252	₩7601A50	
MD7601A12	12.5V	1.8A	±2%	TO-252	₩7601A12	
MD7601B30	3.0V	1.8A	±2%	SOT-223	₩7601B30	
MD7601B33	3.3V	1.8A	±2%	SOT-223	₩7601B33	
MD7601B36	3.6V	1.8A	±2%	SOT-223	₩7601B36	
MD7601B40	4.0V	1.8A	±2%	SOT-223	₩7601B40	
MD7601B50	5.0V	1.8A	±2%	SOT-223	₩7601B50	
MD7601B12	12.0V	1.8A	±2%	SOT-223	₩7601B12	
MD7601C30	3.0V	1.8A	±2%	SOT-223	₩7601C30	
MD7601C33	3.3V	1.8A	±2%	SOT-223	₩7601C33	
MD7601C36	3.6V	1.8A	±2%	SOT-223	₩7601C36	
MD7601C40	4.0V	1.8A	±2%	SOT-223	₩7601C40	

MD7601C50	5.0V	1.8A	±2%	SOT-223	₩7601C50
MD7601C12	12.0V	1.8A	±2%	SOT-223	₩7601C12

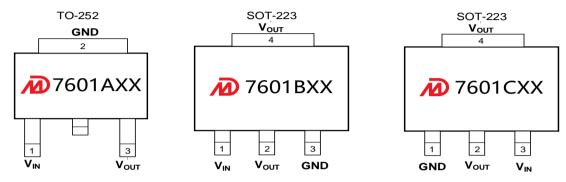
Notes:

1* Customer can request to customize the output voltage ranged from 1.2V to 15V if desired voltage is not found in the selections.

2* Customer can request customization of package choice.

3* Please pay attention to the MARKING of the product package type.

■ PIN CONFIGURATION (TOP VIEW)



■ Absolute Maximum Ratings (Unless otherwise indicated: Ta=25°C)

PARAMETER	SYMBOL	RATINGS	UNITS	
Input Voltage	Vin	-0.3 ~ 45	V	
Output Voltage	V _{OUT}	Vss-0.3 ~ VIN+0.3V		
Power Dissipation	Po	TO 252 1800 SOT 223 1500	mW	
Operating Ambient Temperature	T _{opr}	-40 ~ +85	°C	
Storage Temperature	T _{stg}	-40 ~ +125		
ESD Protection	ESD HBM	2000	V	

Note: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device.

ELECTRICAL CHARACTERISTICS

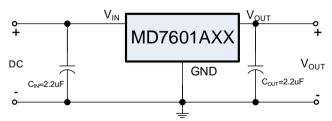
PARAMETER	SYMBOL	CONDIT	MIN.	TYP.	MAX.	UNIT	
Output Voltage*1	V _{OUT(S)}	$V_{IN}=V_{OUT(S)}+2V$, $I_{OUT}=10mA$		V _{OUT(S)} × 0.98	Vout(s)	V _{OUT(S)} × 1.02	V
Dropout Voltage*2	V _{DROP}	I _{OUT} =1mA			4	8	mV
		lout=		1000	1500		
Line Regulation	$\frac{\Delta V_{OUT}}{\Delta V_{IN} \bullet V_{OUT(s)}}$	V _{OUT(S)} +2V≤V _{IN} ≤40V Iout =1mA			0.01	0.02	%/V
Load Regulation	ΔVουτ2	V _{IN} =V _{OUT(S)} +2V 1mA≤I _{OUT} ≤300mA	V _{OUT(S)} ≤10V		20	80	₩V
			V _{OUT(S)} >10V		85	150	
Temperature Stability	$\frac{\Delta V_{OUT}}{\Delta T_a \bullet V_{OUT(s)}}$	$V_{IN} = V_{OUT(S)}+2V$, $I_{OUT}=10mA$ -40°C≤T _a ≤85°C			±50		ppm/ ℃
GND Current	I _{GND}	no load	V _{OUT(S)} ≤10V		10	30	uA
			V _{OUT(S)} >10V		12	30	
		I _{OUT} =100mA			460		
Input Voltage	V _{IN}			2.2		40	V
Maximum Output Current	IOUTMAX			1			_
Current Limit*3	I _{LIM}	V _{IN} = V _{OUT(S)} +2V, V _{OUT} = 0.95 ×V _{OUT(S)}			1.8		A
Short Circuit Current ^{*4}	I _{SHORT}	VIN=VOUT(S)+2V VOUT=0V	V _{OUT(S)} ≤10V		50		mA
			Vout(s)>10V		75		
Power Supply Rejection Ratio		f=10Hz, V _{OUT(S)} =3.6V			84		
	PSRR	f=100Hz, V _{OUT(S)} =3.6V			80		dB
		f=1kHz, V _{OUT(S)} =3.6V			58		
Over Temperature Protection	OTP	I _{OUT} =1mA			180		°C

MD7601 Series (Unless otherwise indicated: T_a=25℃)

Notes:

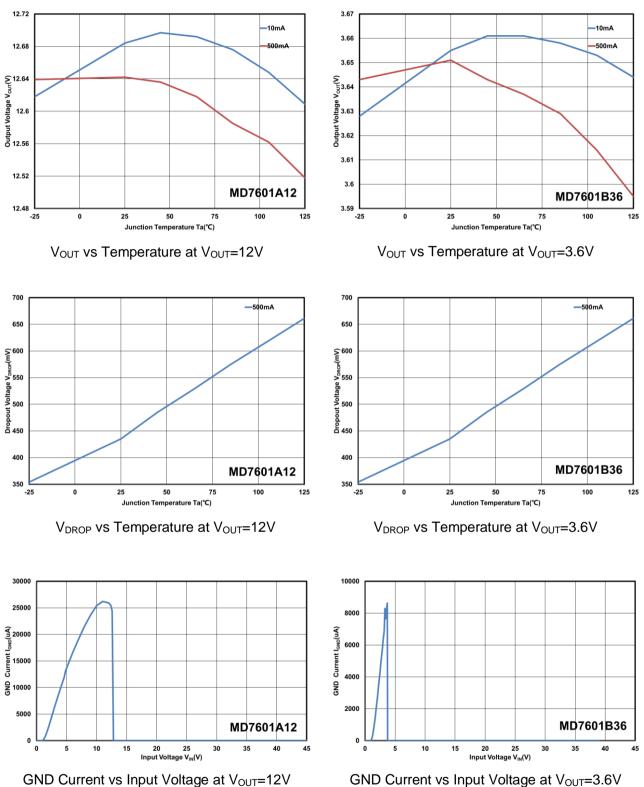
- 1. $V_{OUT(S)}$: Output voltage when $V_{IN}=V_{OUT}+2V$, $I_{OUT}=1$ mA.
- 2. $V_{DROP}=V_{IN1}$ $(V_{OUT(S)} \times 0.98)$ where V_{IN1} is the input voltage when $V_{OUT} = V_{OUT(S)} \times 0.98$.
- 3. ILIM: Output current when $V_{\text{IN}}{=}V_{\text{OUT}(S)}{+}2V$ and $V_{\text{OUT}}{=}0.95^{*}V_{\text{OUT}(S)}{.}$
- 4. VOUT pin should be shorted to GND pin, and the impedance between them is less than 0.1 ohm.

■ TYPICAL APPLICATIONS

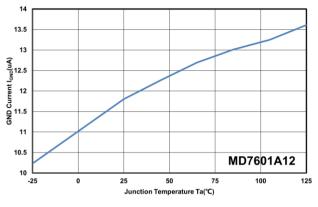


Notes on Use

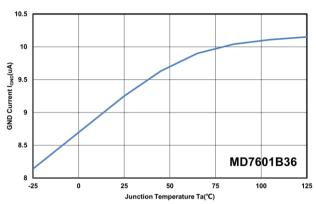
Input Capacitor (C_{IN}): 2.2 μ F above Output Capacitor (C_{OUT}): 2.2 μ F above



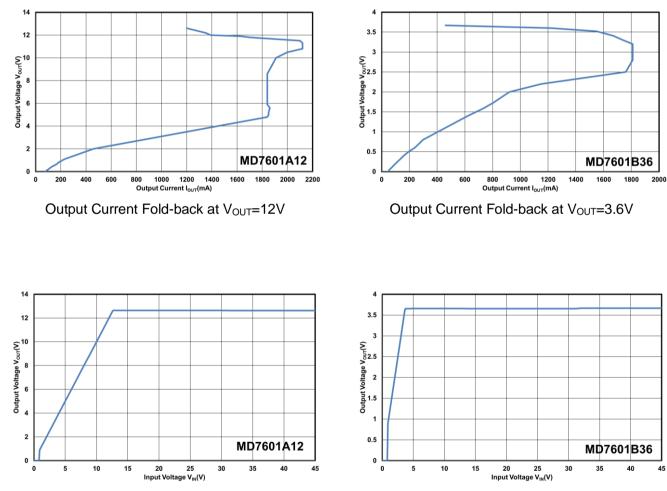
Test Conditions: VIN=VOUT+2.0V, CIN=2.2µF, COUT=2.2µF, unless otherwise indicated.



GND Current vs Temperature at VOUT=12V



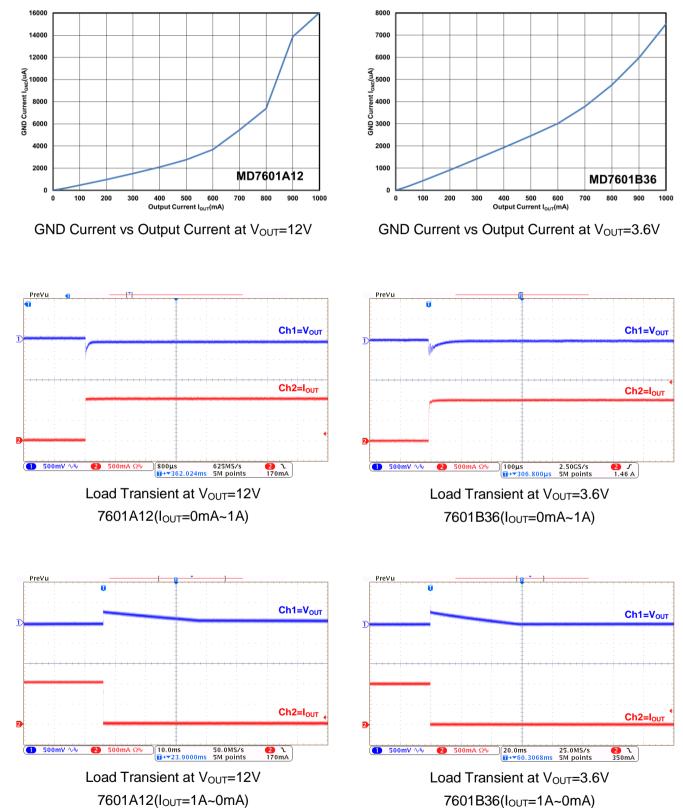
GND Current vs Temperature at V_{OUT}=3.6V

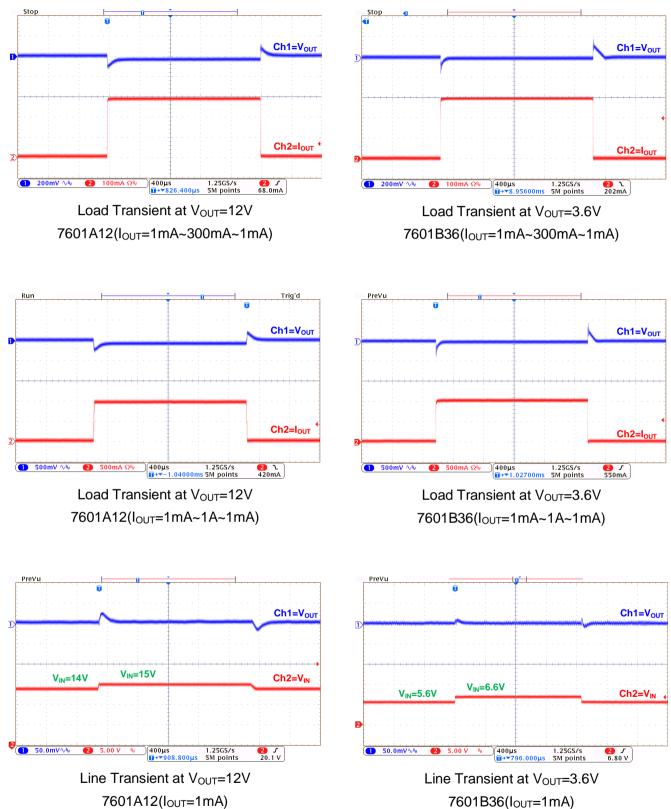


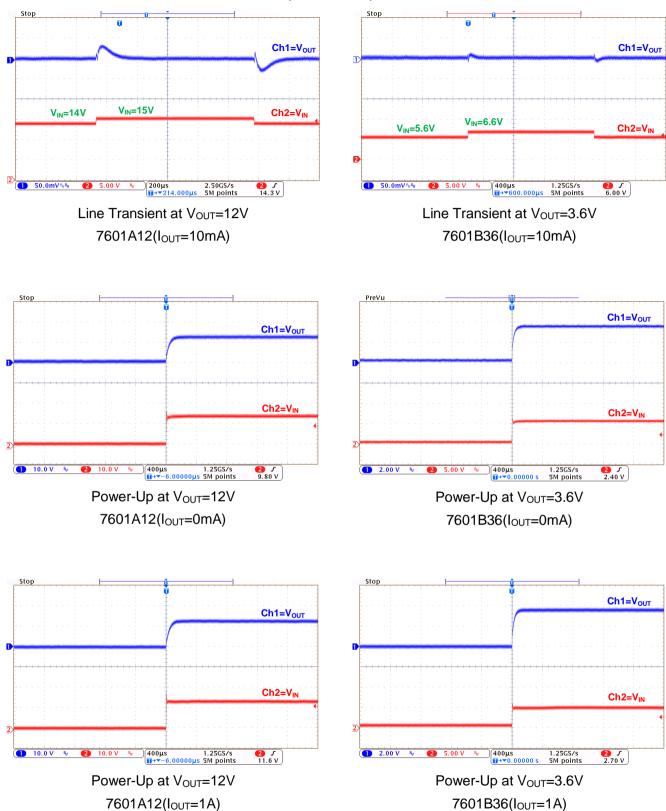
Output Voltage vs Input Voltage at VOUT=12V

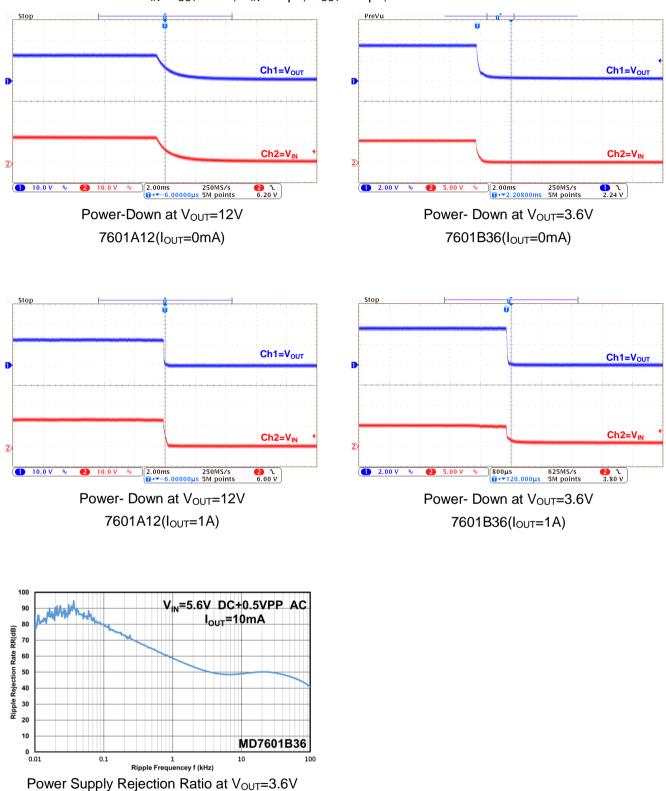
Output Voltage vs Input Voltage at VOUT=3.6V

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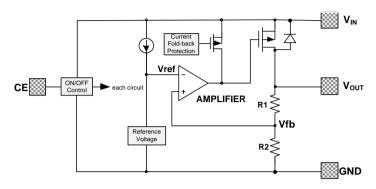




OPERATIONAL EXPLANATION

1. Output voltage control

The voltage divided by resistors R1 and R2 is compared with the internal reference voltage by the error amplifier. The amplifier output then drives the P-channel MOSFET connected to the V_{OUT} pin. The output voltage at the V_{OUT} pin is regulated by this negative feedback system. The current limit circuit and short protect circuit operate in relation to output current level. Further, the IC's internal circuitry can be in operation or shutdown modes controlled by the CE pin's signal.



2. Pass transistor

The pass transistor with low turn-on resistance used in MD83XX is a P-channel MOSFET. If the potential on V_{OUT} pin is higher than VIN, it is possible that IC will be destroyed due to reverse current which is caused by parasitic diodes between V_{IN} and V_{OUT} . Therefore, the V_{OUT} pin potential exceeds V_{IN} +0.3V is not allowed.

3. Current foldback and over temperature protection

The MD83XX series includes a combination of a fixed current limiter circuit and a foldback circuit, which aid the operations of the current limiter and circuit protection. When the load current reaches the current limit level, the fixed current limiter circuit operates and output voltage drops. As a result of this drop in output voltage, the foldback circuit operates, output voltage drops further and output current decreases. This design can prevent the chip be damaged due to over temperature, moreover, the heat dissipation is limited by the package type.

Special attention should be paid to that the product of the dropout voltage on the chip and the output current must be smaller than the heat dissipation. If power consumption on the chip is more than the heat dissipation, OTP will protect the chip from damaging due to over temperature.

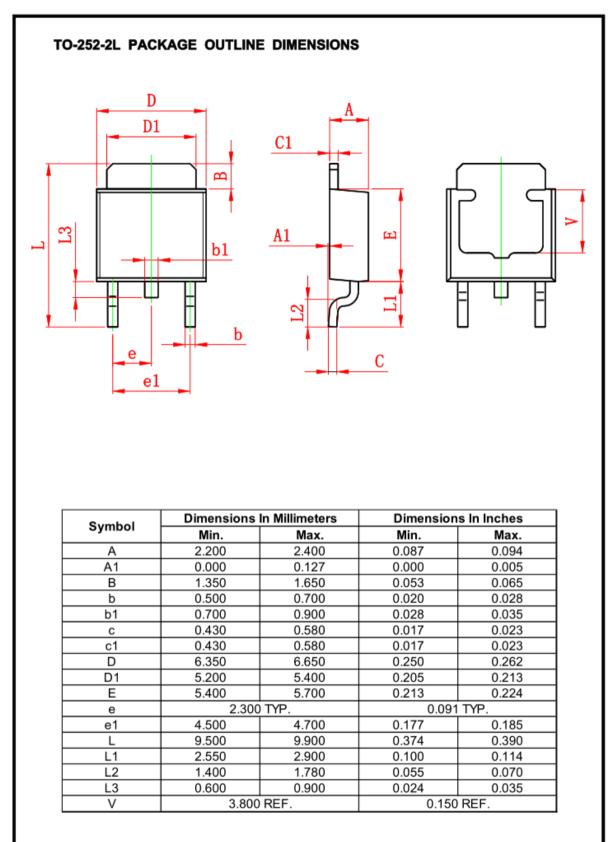
Notes:

1. The input and output capacitors should be placed as close as possible to the IC.

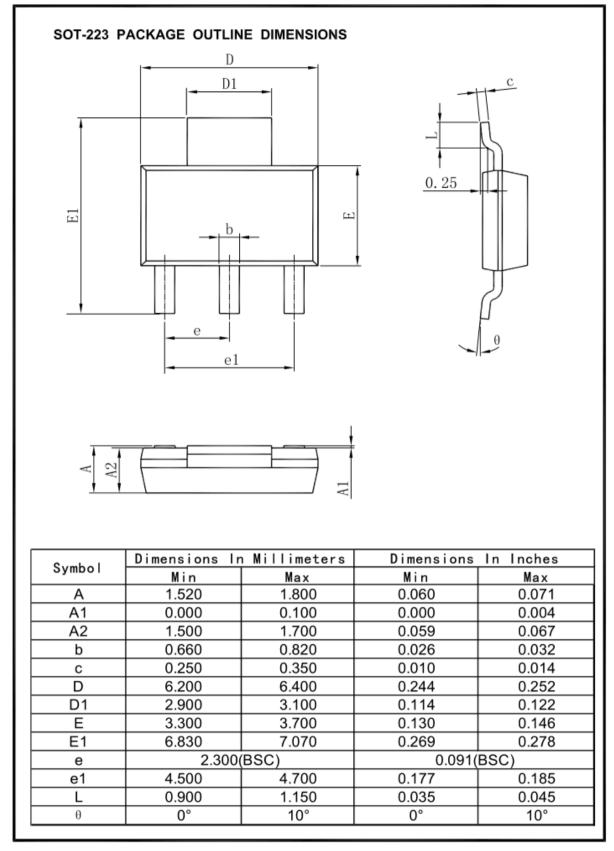
2. If the impedance of the power supply is high, which is caused by forgetting installing input capacitor or installing too small value capacitor, the oscillation may occur.

3. Pay attention to the operation conditions of input and output voltage and load current, such that the power consumption in the IC should not exceed the allowable power consumption of the package even though the chip has short circuit protection.

4. IC has a built-in anti-static protection (ESD) circuit, but please do not add excessive stress to the IC.



PACKAGING INFORMATION(Continued)



For the newest datasheet, please see the website: Version V1.5: 20210930

www.md-ic.com.cn